

### **REMARKS**

This responds to the Office Action mailed on October 4, 2004.

Claims 1, 5, 9, and 13 are amended, no claims are canceled, and no claims are added; as a result, claims 1-18 remain pending in this application.

#### **§102 Rejection of the Claims**

Claims 1-3, 5-7, 9-11, 13-15, and 17-18 were rejected under 35 USC § 102(b) as being anticipated by Adams et al. (U.S. 5,026,748).

The rejection states that “Adams discloses a thermally conductive resin.” A pair of dictionary definitions from 1992 are provided to suggest that resin and grease are similar. Adams appears to show a number of examples of resin that is cured to a hardened state to form an adhesive bond. Adams also appears to show devices that in operation would conduct heat only through a cured or otherwise hardened, non-viscous adhesive material.

Adams does not show, teach or suggest a non-curable viscous matrix material including a substantial volume fraction of thermal grease. Adams also does not show, teach or suggest a viscous matrix material for indefinitely maintaining a level of viscosity including a substantial volume fraction of thermal grease. Adams also does not show, teach or suggest a volume of a non-adhesive viscous matrix material including a substantial volume fraction of thermal grease. Adams also does not show, teach or suggest conducting heat through a thermal conduction material, wherein the thermal conduction material includes a substantial volume fraction of viscous thermal grease material.

In contrast, Applicant’s claims 1 and 13 as amended, include a non-curable viscous matrix material including a substantial volume fraction of thermal grease. Further in contrast, Applicant’s claim 5 as amended, includes a viscous matrix material for indefinitely maintaining a level of viscosity including a substantial volume fraction of thermal grease. Further in contrast, Applicant’s claim 9 as amended, includes a volume of a non-adhesive viscous matrix material including a substantial volume fraction of thermal grease. Further in contrast, Applicant’s claim 17, includes conducting heat through a thermal conduction material, wherein the thermal conduction material includes a substantial volume fraction of viscous thermal grease material.

Because the Adams reference does not show every element of Applicant's independent claims, a 35 USC § 102(b) rejection is not supported. Reconsideration and withdrawal of the rejection is respectfully requested with respect to Applicant's independent claims 1, 5, 9, 13, and 17. Additionally, reconsideration and withdrawal of the rejection is respectfully requested with respect to the remaining claims that depend therefrom as depending on allowable base claims.

§103 Rejection of the Claims

Claims 4, 8, 12, and 16 were rejected under 35 USC § 103(a) as being unpatentable over Adams et al. (U.S. 5,026,748) in view of Ameen et al. (U.S. 5,545,473). Applicant respectfully submits that the additional reference of Ameen fails to cure the deficiencies of Adams as outlined above.

Because the cited references, either alone or in combination, do not show every element of Applicant's claims, a 35 USC § 103(a) rejection is not supported by the references. Reconsideration and withdrawal of the rejection are respectfully requested with respect to claims 4, 8, 12, and 16.

Conclusion

Applicant respectfully submits that the claims are in condition for allowance and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney at (612) 373-6944 to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

CHIA-PIN CHIU ET AL.

By their Representatives,

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Date 12-6-04

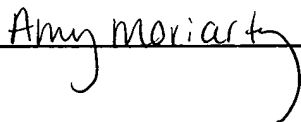
By



David C. Peterson  
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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 6<sup>th</sup> day of December, 2004.

Name



Signature

